

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT								
NATURE OF CONVEYANCE:	ASSIGNMENT								
CONVEYING PARTY DATA									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Manuel Carmona</td> <td>07/20/2007</td> </tr> <tr> <td>Anton Legen</td> <td>07/16/2007</td> </tr> <tr> <td>Ingo Wennemuth</td> <td>07/16/2007</td> </tr> </tbody> </table>		Name	Execution Date	Manuel Carmona	07/20/2007	Anton Legen	07/16/2007	Ingo Wennemuth	07/16/2007
Name	Execution Date								
Manuel Carmona	07/20/2007								
Anton Legen	07/16/2007								
Ingo Wennemuth	07/16/2007								
RECEIVING PARTY DATA									
Name:	Infineon Technologies AG								
Street Address:	St.-Martin-Str. 53								
City:	Munich								
State/Country:	GERMANY								
Postal Code:	81669								
PROPERTY NUMBERS Total: 1									
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>11630930</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	11630930				
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CORRESPONDENCE DATA									
Fax Number:	(612)573-2005								
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>									
Phone:	612-573-2000								
Email:	cschlotz@dbclaw.com								
Correspondent Name:	Steven E. Dicke								
Address Line 1:	Fifth St. Towers, 100 South Fifth St.								
Address Line 2:	Suite 2250								
Address Line 4:	Minneapolis, MINNESOTA 55402								
ATTORNEY DOCKET NUMBER:	I431.189.101								
NAME OF SUBMITTER:	Steven E. Dicke								

Total Attachments: 2
 source=ExecutedAssignment#page1.tif

500325868

PATENT
REEL: 019629 FRAME: 0501

CH \$40.00 11630930

ASSIGNMENT

For good and valuable consideration, I, Manuel Carmona, a citizen of Spain, residing at Jaume Pau 4, Santa Coloma de Cervello, Barcelona, Spain, Anton Legen, a citizen of Germany, residing at Oefelestr. 14, Muenchen, Germany, and Ingo Wennemuth, a citizen of Germany, residing at Hoehenstadter Strasse 15, Muenchen, Germany, hereinafter individually or collectively referred to as "Assignor";

Hereby sell, assign and transfer to **Infineon Technologies AG**, a corporation organized and existing under the laws of Germany, having its principal place of business at St.-Martin-Str. 53, 81669 Munich, Germany, hereinafter "Assignee", its successors, assigns and legal representatives, the entire right, title and interest in and for the United States and all foreign countries, in and to any and all improvements which are disclosed in the application for United States Letters Patent, which has been executed by the undersigned and

filed on December 27, 2006

US. Serial No. 11/630,930,

entitled: SEMICONDUCTOR DEVICE WITH HOUSING AND A SEMICONDUCTOR CHIP PARTLY EMBEDDED IN A PLASTIC HOUSING COMPOSITION, AND METHOD FOR PRODUCING THE SAME

and in and to said application and all divisional, continuing, substitute, renewal, reissue, and all other applications for Letters Patent which have been or shall be filed in the United States and all foreign countries on any of said improvements; and in and to all original and reissued patents which have been or shall be filed in the United States and all foreign countries on said improvements;

Agree that said Assignee may apply for and receive Letters Patent for said improvements in its own name; and that, when requested, without charge to but at the expense of said Assignee, its successors, assigns and legal representatives, to carry out in good faith the intent and purpose of this assignment, the undersigned will execute all divisional, continuing, substitute, renewal, reissue, and all other patent applications on any and all said improvements; execute all rightful oaths, assignments, powers of attorney and other papers; communicate to said Assignee, its successors, assigns, and legal representatives, all facts known to the undersigned relating to said improvements and the history thereof; and generally do everything possible which said Assignee, its successors, assigns or legal representatives shall consider desirable for aiding in securing and maintaining proper patent protection for said improvements and for vesting title to said improvements and all applications for patents and all patents on said improvements, in said Assignee, its successors, assigns and legal representatives; and

Covenant with said Assignee, its successors, assigns and legal representatives that no assignment, grant, mortgage, license or other agreement affecting the rights and property herein conveyed has been made to others by the undersigned, and that full right to convey the same as herein expressed is possessed by the undersigned.

SIGNATURE: _____ DATE: _____
NAME: Manuel Carmona

SIGNATURE: Anton Legen DATE: 2007/07/16
NAME: Anton Legen

SIGNATURE: Ingo Wennemuth DATE: 2007/07/16
NAME: Ingo Wennemuth

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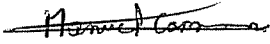
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NAME: Manuel Carmona

SIGNATURE: _____ DATE: _____
NAME: Anton Legen

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NAME: Ingo Wennemuth